


Application Data Sheet**Application Information**

Application Type::	Regular
Subject Matter::	Utility
Suggested Group Art Unit::	N/A
CD-ROM or CD-R?::	None
Sequence submission?::	None
Computer Readable Form (CRF)?::	No
Title::	METHOD FOR FORMING COMPACT FROM POWDER AND MOLD APPARATUS (FOR POWDER MOLDING (AS AMENDED))
Attorney Docket Number::	09864/0202607-US0
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	Fig. 1
Total Drawing Sheets::	3
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Takashi
Family Name::	Nakai
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Country of Residence::	Japan
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City of mailing address:: Niigata-shi

State or Province of mailing address:: Niigata

Country of mailing address:: Japan

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Applicant Authority Type:: Inventor

Primary Citizenship Country:: Japan

Status:: Full Capacity

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Postal or Zip Code of mailing address:: 950-8640

Correspondence Information

Correspondence Customer Number:: 07278

Representative Information

Representative Customer Number:: 07278

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	National Stage of	PCT/JP2003/014643	11/18/03

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	2002-338621	11/21/02	No

Assignee Information

Assignee name:: Mitsubishi Materials Corporation
 Street of mailing address:: 5-1, Ohtemachi 1-chome
 Chiyoda-ku,
 City of mailing address:: Tokyo
 Country of mailing address:: Japan